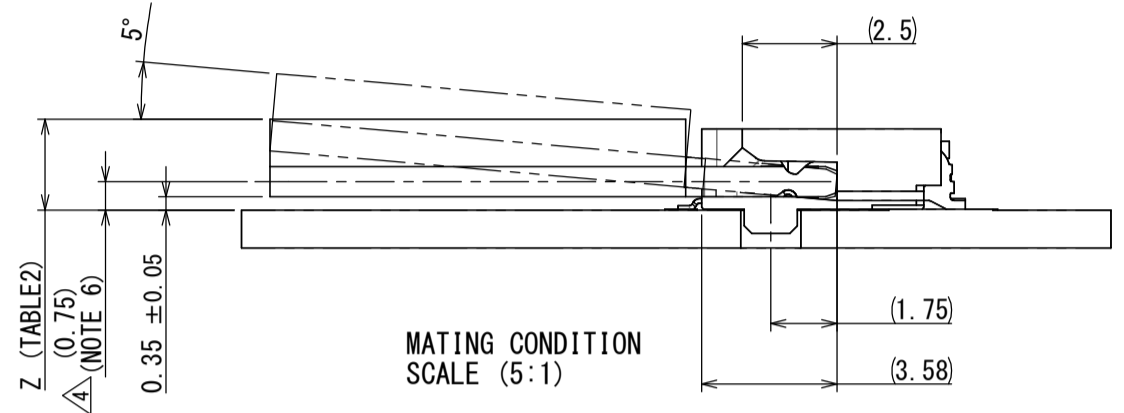
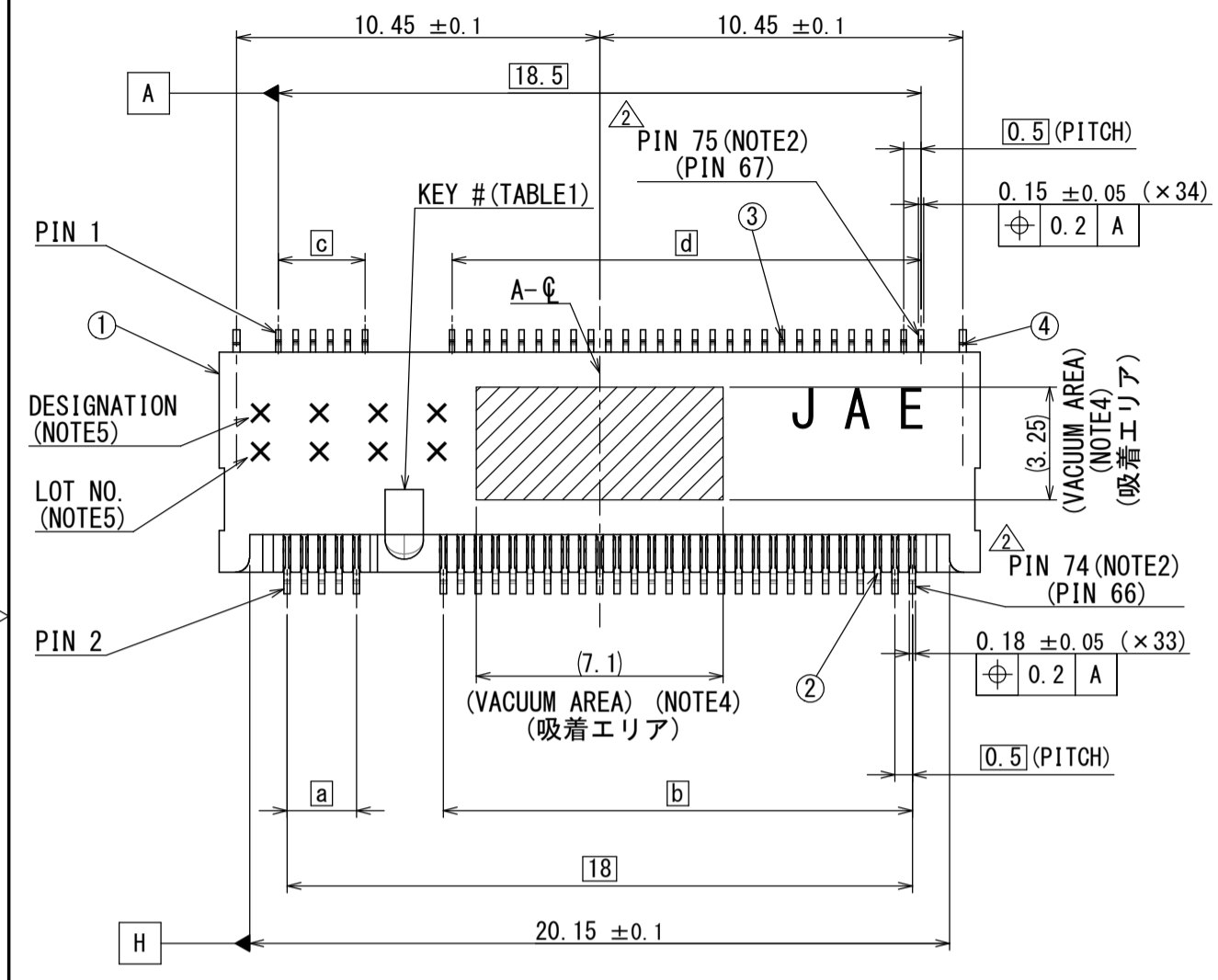


SJ113567  
(DRAWING NO.)

版数 VER.	年月日 DATE	図号 CN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	19/AUG/2013	007107	Correction of errors.		S. YAMAGUCHI	R. KATOU	T. SHINDOU
3	26/JUN/2014	008839	Specification is changed.		S. YAMAGUCHI	M. SASAKI	T. SHINDOU
4	16/MAR/2015	012411	Add KEY version (KEY-A, KEY-M) etc.		S. YAMAGUCHI	M. SASAKI	T. SHINDOU

DESIGNATION

**SM3ZS067U215**※  
 SERIES シリーズ  
 Z: LIF TYPE  
 Z: 低挿入タイプ  
 S: STANDARD  
 NO. OF CONTACTS 芯数  
 MOUNTING TYPE 実装タイプ  
 U: ON BOARD TYPE  
 KEY POSITION TYPE: A, B, E, M  
 CONTACT FINISH 接点仕上げ  
 A: Au (0.13 μm MIN)  
 B: Au (0.25 μm MIN)  
 PRODUCT HEIGHT 製品高さ  
 215: 2.15mm  
 310: 3.10mm  
 410: 4.10mm



NOTE5. PRODUCTION LOT No. & MODIFY CODE AS INDICATED.  
 (Ex. LOT NO.) T 5 Y B  
 LOT NUMBER OF CURRENT DAY (SEE TABLE 3)  
 MONTH (1 TO 9 FOR JAN. TO SEPT. RESPECTIVELY, OCT.:0, NOV.:X, DEC.:Y)  
 YEAR (LAST DIGIT ONLY)  
 MANUFACTURE CODE  
 (DESIGNATION) S M 3 B  
 KEY POSITION TYPE: A, B, E, M  
 SERIES PREFIX

TABLE 1

KEY#	X	a	b	c	d
A	+6.625	1	14.5	1.5	14.5
B	+5.625	2	13.5	2.5	13.5
E	+2.625	5	10.5	5.5	10.5
M	-6.125	14	1.5	14	2

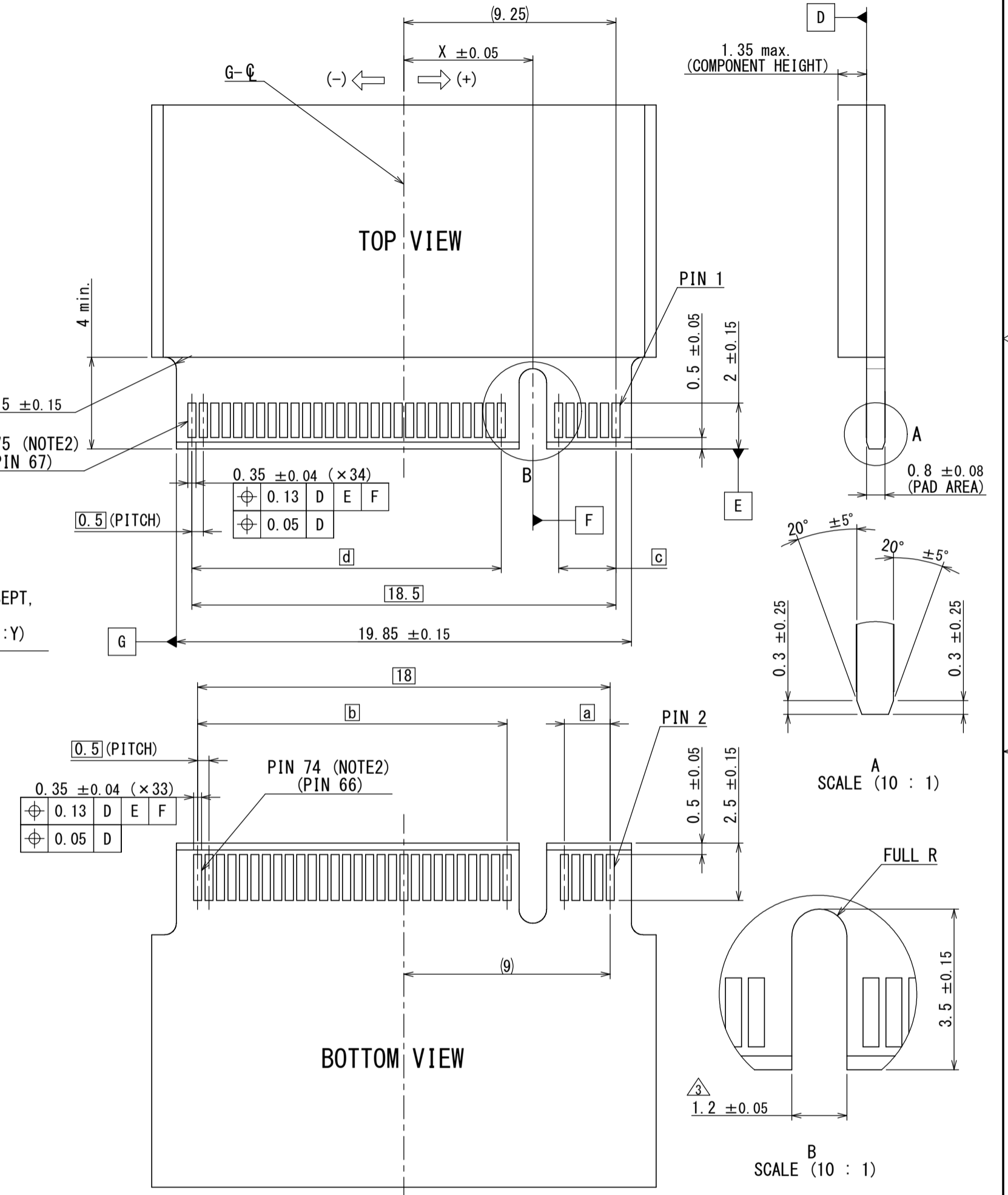
TABLE 2

COMPONENT HEIGHTS FOR MODULES	Z
1.2 MAX	2.45 MAX RSS
1.35 MAX	2.60 MAX RSS
1.5 MAX	2.75 MAX RSS

TABLE 3. LOT NUMBER CODE OF CURRENT DAY (END OF LOT No.)

DAY CODE	1	2	3	4	5	6	7	8	9	10	
	1	2	3	4	5	6	7	8	9	0	
DAY CODE	11	12	13	14	15	16	17	18	19	20	
	A	B	C	D	E	F	G	H	J	K	
DAY CODE	21	22	23	24	25	26	27	28	29	30	31
	L	M	N	P	Q	R	S	T	V	W	X

NOTE1. THE COPLANARITY OF CONTACT AND HOLD DOWN SHALL BE 0.1 MAXIMUM ON THE SURFACE TABLE.  
 NOTE2. THIS NUMBER IS PIN-OUT NUMBER DEFINED BY NGFF SPECIFICATION.  
 NOTE3. THIS CONNECTOR IS HALOGEN FREE CORRESPONDENCE PRODUCT.  
 NOTE4. THIS AREA SHALL NOT SHOW ANY BURRS AND UNEVEN SURFACE BY EJECTOR PIN MARK, TOOL PARTING LINE, AND ANY OTHER FACTORS.  
 NOTE6. THE HEIGHT TO THE MODULE CARD CENTER FROM P.C.B. SURFACE.



Pattern prohibition area  
 APPLICABLE P.C.B. DIMENSION (REF.) SCALE (5:1)

符号 No.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	HOLD DOWN	2	COPPER ALLOY	TIN PLATING OVER NI	
3	TOP SIDE CONTACT	34	COPPER ALLOY	CONTACT AREA: REFER TO DESIGNATION SOLDERING AREA: Au FLASH OVER Ni	
2	BOTTOM SIDE CONTACT	33	COPPER ALLOY	CONTACT AREA: REFER TO DESIGNATION SOLDERING AREA: Au FLASH OVER Ni	
1	INSULATOR	1	THERMO PLASTIC		

仕様書 (SPECIFICATION) 第1版 (ORIGINAL DATE) 05/MAR/2013  
 製図 DR. 担当 CHK. S. YAMAGUCHI  
 査閲 APPD. R. KATOU  
 承認 APPD. T. SHINDOU  
 名称 (TITLE) SM3ZS067U215※※※ NGFF Single-Sided modules  
 製図 DR. S. YAMAGUCHI  
 担当 CHK. R. KATOU  
 査閲 APPD. M. SASAKI  
 承認 APPD. T. SHINDOU  
 図面番号 (DRAWING NO.) SJ113567

WISDOM承認 2015/04/01